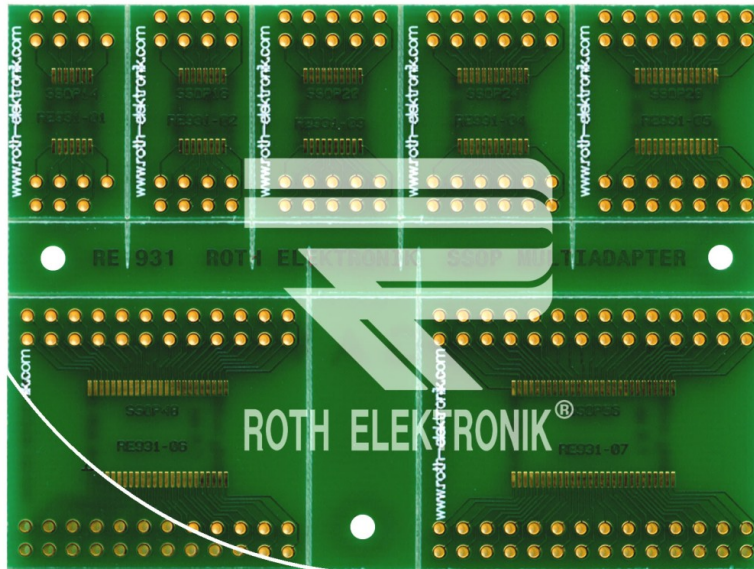


SSOP-SMD Multiadapter (shrink small outline package)



RE931

- EPOXY fibre glass FR4 1.5 mm double-sided 35 µm CU (pth)
- solder and component side with chem. NI/AU surface and solder stop mask
- hole dia 1.00 mm
- adapter for 7 different SSOP
- pitch 0.65 mm / 0.635 mm
- pre-scratched rated break points for the separation of individual modules from the board
- size 61.40 x 81.70 mm

Modul-No	Pitch	mil	Pin/Quantity	Size (mm)
RE931-01	0.65	22.5	14	5.3 (208 mil)
RE931-02	0.65	22.5	16	5.3 (208 mil)
RE931-03	0.65	22.5	20	5.3 (208 mil)
RE931-04	0.65	22.5	24	5.3 (208 mil)
RE931-05	0.65	22.5	28	5.3 (208 mil)
RE931-06	0.635	25.7	48	7.5 (300 mil)
RE931-07	0.635	25.7	56	7.5 (300 mil)